Special Issue

Emerging Techniques in Diagnostic Medical Imaging: Quantitative Imaging, Radiomics, and Artificial Intelligence

Message from the Guest Editors

We are pleased to announce a Special Issue entitled **"Emerging Techniques in Diagnostic Medical Imaging: Quantitative Imaging, Radiomics, and Artificial Intelligence"**, to be published by the journal *Applied Sciences* (MDPI). We invite research contributions from cross-disciplinary scientists and professionals involved in diagnostic medical imaging. Clinically oriented studies, pictorial reviews, systematic reviews, and metanalyses mainly on quantitative imaging and the application of radiomics and artificial intelligence in CT and MRI are welcome. We also invite research contributions focused on developing deep-learning models and 3D model printing. Research areas may include (but are not limited to) the following:

- Studies on quantitative CT/MRI imaging;
- Radiomics studies;
- Dual-energy CT and photon-counting CT;
- Advanced MRI sequences;
- Perfusion CT;
- Artificial intelligence in diagnostic imaging;
- 3D model printing;
- Texture analysis and machine learning in CT and MRI.

Guest Editors

Dr. Federica Vernuccio

Dr. Roberto Cannella

Dr. Domenico Albano

Deadline for manuscript submissions

closed (31 October 2023)

Applied Sciences

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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